NCP2823 Series Evaluation Board User's Manual



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EVAL BOARD USER'S MANUAL

Overview

The NCP2823A/B are cost effective mono audio power amplifiers designed for portable electronic devices. NCP2823A is optimized for 8 Ω operation and NCP2823B can operate with speaker impedance down to 4.0 Ω . For Instance, NCP2823B is capable of delivering 3 W of continuous average power to a 4.0 Ω from a 5.0 V supply in a Bridge Tied Load (BTL) configuration. Under the same conditions, NCP2823A can provide 1.5 W to an 8.0 Ω BTL load with less than 1% THD+N. For cellular handsets or



Figure 1. NCP2823AGEVB Board Picture

PDAs it offers space and cost savings because no output filter is required when using inductive transducers. With more than 95% efficiency and very low shutdown current, it increases the lifetime of your battery and drastically lowers the junction temperature.

The intent of the evaluation boards is to illustrate typical operation of the NCP2823 device for laboratory characterization. The NCP2823 Series Evaluation Board schematic is depicted in Figure 3.

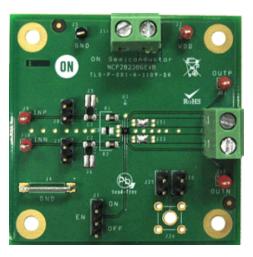


Figure 2. NCP2823BGEVB Board Picture

BOARD SCHEMATIC

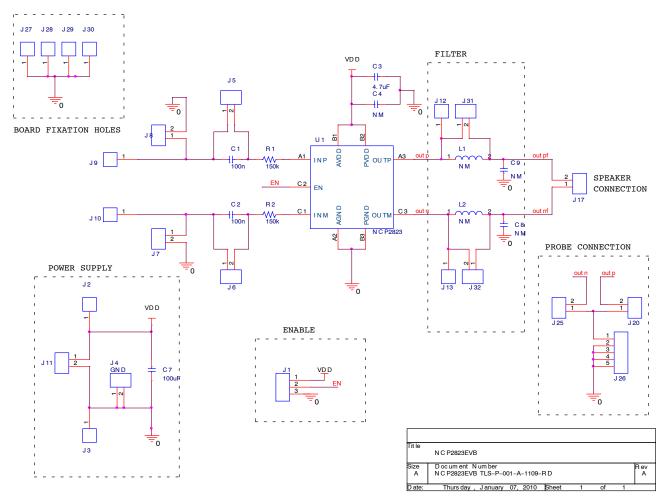


Figure 3. NCP2823 Series Evaluation Board Schematic

OPERATION

The operating power supply of the NCP2823 is from 2.5 to 5.5 V. The absolute maximum input voltage is 7.0 V. A power supply set to 3.6 V and current limit set to at least 1.5 A must be connected to J11 connector to powering the NCP2823 Series Evaluation Board. Also to compensate for parasitic inductance of wires between the power supply and the evaluation board it is highly recommended to connect a 470 μ F electrolytic capacitor to bypass J11 terminal. Like this the device can be evaluate under powering condition very similar that battery power supplies.

Performances of EVB Solution

To be as close as possible with final handset application, the design of this power conversion solution used small size footprints where possible. Changing components may positively or negatively impact the evaluation board performance, illustrated in Figure 4 to 9. For more information please refer to the NCP2823 datasheet.

Table 1. BOARD CONNECTIONS

INPUT POWER

Symbol	Descriptions		
J11–1	This is the positive connection for power supply. The leads (positive + ground) to the input supply should be twisted and kept as short as possible.		
J11–2	This is the return connection for the power supply (Ground signal)		
J4	J4 Ground clip		

AUDIO

Symbol	Descriptions		
J9	Positive Audio input		
J10	Negative Audio input		
J17–2	Positive Audio output		
J17–1	Negative Audio output		

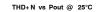
SWITCHES SETUP

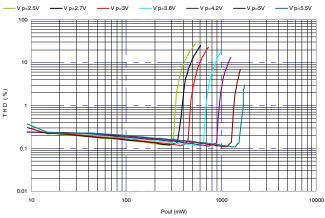
Symbol	Switch Descriptions		
J1	Enable		
J5	Short input capacitor on positive input		
J6	Short input capacitor on negative input		
J7	Connect the positive audio input to Gnd		
J8	Connect the negative audio input to Gnd		
J31	Short filter on positive output		
J32	Short filter on negative output		
J25	Connect negative output to Probe connection (J26)		
J20	Connect Positive output to Probe connection (J26)		

TEST POINT

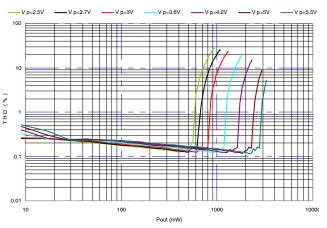
Symbol	Switch Descriptions		
J3	This test point is directly connected to the GND		
J2	This test point is directly connected to the Vdd pin		
9L	This test point is connected to the positive audio input		
J10	This test point is connected to the negative audio input		
J12	This test point is connected to the positive audio output		
J13	This test point is connected to the negative audio output		
J26	Probe connection		

TYPICAL OPERATING CHARACTERISTICS



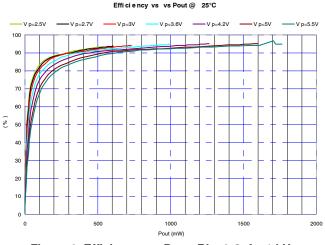




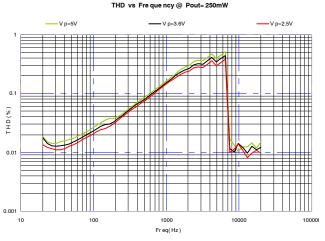


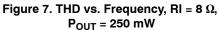
THD+N vs Pout @ 25°C

Figure 5. THD vs. $\text{P}_{\text{OUT}},$ RI = 4 $\Omega,$ f = 1 kHz









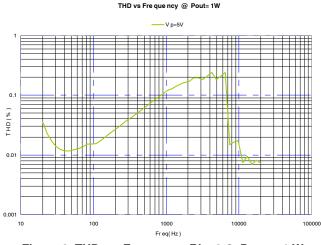


Figure 8. THD vs. Frequency, RI = 8 Ω , P_{OUT} = 1 W

PSRR vs. FreqInputgnd (100nF)

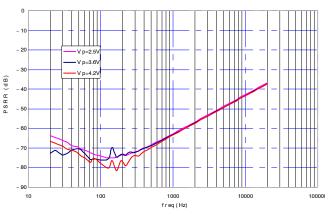


Figure 9. PSRR vs. Frequency

PCB LAYOUT

As with all Class D amplifier, care must has been observed to place the components on the PCB and layout the critical nodes. The evaluation board is made of 4 PCB layers where first internal layer is a GND. Figure 10, Figure 12 and Figure 13 show the layout of the NCP2823 Series evaluation board. For more specific layout guidelines please refer to the NCP2823 datasheet.

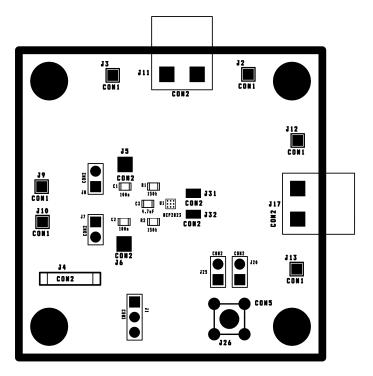


Figure 10. Assembly Layer TOP

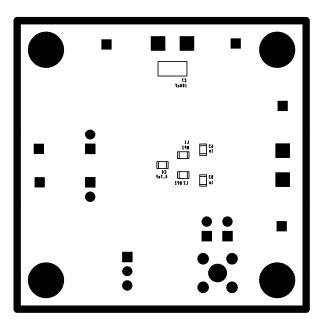


Figure 11. Assembly Layer BOTTOM

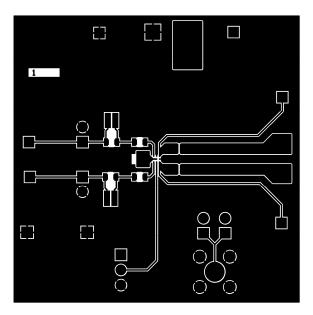


Figure 12. Top Layer Routing

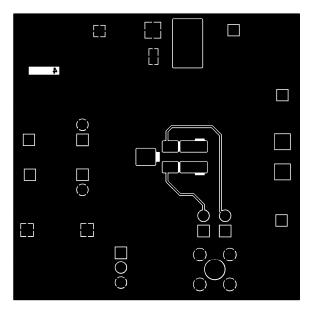


Figure 13. Bottom Layer Routing

Qty	Ref Des.	Description	Size	Manufacturer	Part Number
1	U1	NCP2823	CSP-9 1.45 x 1.45 mm	ON Semiconductor	NCP2823
2	C1, C2	Capacitor, Ceramic 100 nF	0603	KEMET	C0603C104K5RAC
2	C4	Capacitor, Ceramic 4.7 μF 6.3 V	0603	KEMET	C0603C475K9PAC
2	R1, R2	Resistor 150k 1%	0603	Std	Any supplier possible
2	J11, J17	Mal. SL5.08/2/90B plus Fem. BLZ 5.08/2		Weidmuller	SL5.08/2/90 + BLZ 5.08/2
3	J1	Header 3 pin, 100 mil spacing	0.100 x 2	Std	Std
2	J7, J8	Header 2 pin, 100 mil spacing	0.100 x 2	Std	Std
1	J7	GND Connection		Std	Std
9	J2, J3, J9, J10, J12, J13	Test Point		Std	Std
2	J31, J32	Soldering point must be connected			
1	PCB	PCB 2.0 in x 2.0 in x 1.0 mm, 4 Layers		Any	TLS-P-001-A-1109-RD

Table 2. BILL OF MATERIALS

NOTE: Component J20, J25, J26, L1, L2, C8 and C9 are not mounted on this demokit.

ASSEMBLY TEST PROCEDURE

A power supply set to 3.6 V and current limit set to at least 1.5 A must be connected to J15 connector to powering the NCP2823 Series evaluation board. Also to compensate for parasitic inductance of wires between the power supply and the evaluation board it is highly recommended to connect a 470 μ F electrolytic capacitor to bypass J11 terminal. Like this the device can be evaluate under powering condition very similar that battery power supplies.

These tests are provided in order to guarantee a good assembly of the NCP2823 on its dedicated board, it do not consist in parametric test which is already done at chip level.

SHUTDOWN TEST

Switches setup for shutdown test:

Symbol	Switch Description		
J1 Must be connected to ground (low side)			

*All other switches must be kept floating

Tests:

- 1. Set the switches in the configuration
- 2. Power the board with a 3.6 V power supply limited at 1.5A and bypassed by a 470 μ F electrolytic capacitor.
- 3. Measure the current on the power supply (must be inferior to 1 μ A)

Wake up test

Switches setup for wire mode test:

Symbol	Switch Description		
J1	Must be connected to VDD (high side)		

*All other switches must be kept floating

Tests:

- 4. Set the switches in the configuration
- 5. Power the board with a 3.6 V power supply limited at 1.5 A and bypassed by a 470 μ F electrolytic capacitor.
- 6. Measure DC Output voltage on J12 on J13 and GND. DC Voltage must be equal to 1.8 V
- 7. Measure DC input voltage on J5–2 on J6–2 and GND. DC Voltage must be equal to 1.26 V

SUMMARY

Test	Measurement	Switch Description	
Shutdown test I Supply		l < 1 μA	
Wake up test	VOUTP, VOUTN VJ9, VJ10	VDC = 1.8 V VDC = 1.26 V	

NOTE: For each board a Test Result Table must be fully completed (see the next page)

TEST RESULT TABLE

NCP2823 Assembly Test				
Date		Operator Name		
B	oard Serial Number			
Test No.	Test Name	Results	Value	
1	Shutdown mode test	I Supply		
2	Wake up test	VoutP, VoutN	1.8	
		VJ9, VJ10	1.26	

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